

ABSTRACT

The present invention provides an inspection apparatus capable of adequately positioning an inspection chip to a conductive pattern as an inspection object.

For connecting an electrode pad 1b of an inspection chip 1 with a lead 2a of a package 2, bump electrodes 3 and 4 are first provided at the inspection chip and at the package, respectively. Then, an anisotropic conductor 5 is provided to cover between the bump electrodes 3 and 4, and a conductor film 6 is provided on the anisotropic conductor 5 to extend between the bump electrodes 3 and 4. The anisotropic conductor 5 is thermo-compression bonded to provide an electrical connection between the conductor film 6 and the bump electrodes 3 and 4. This structure may provide a desirable surface of the inspection chip 1 having a sufficiently reduced thickness.

09926347-101701